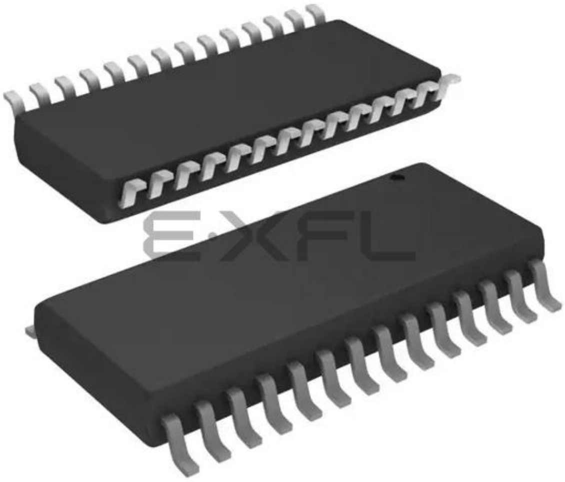
Microchip Technology - DSPIC33FJ12GP202T-I/SO Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

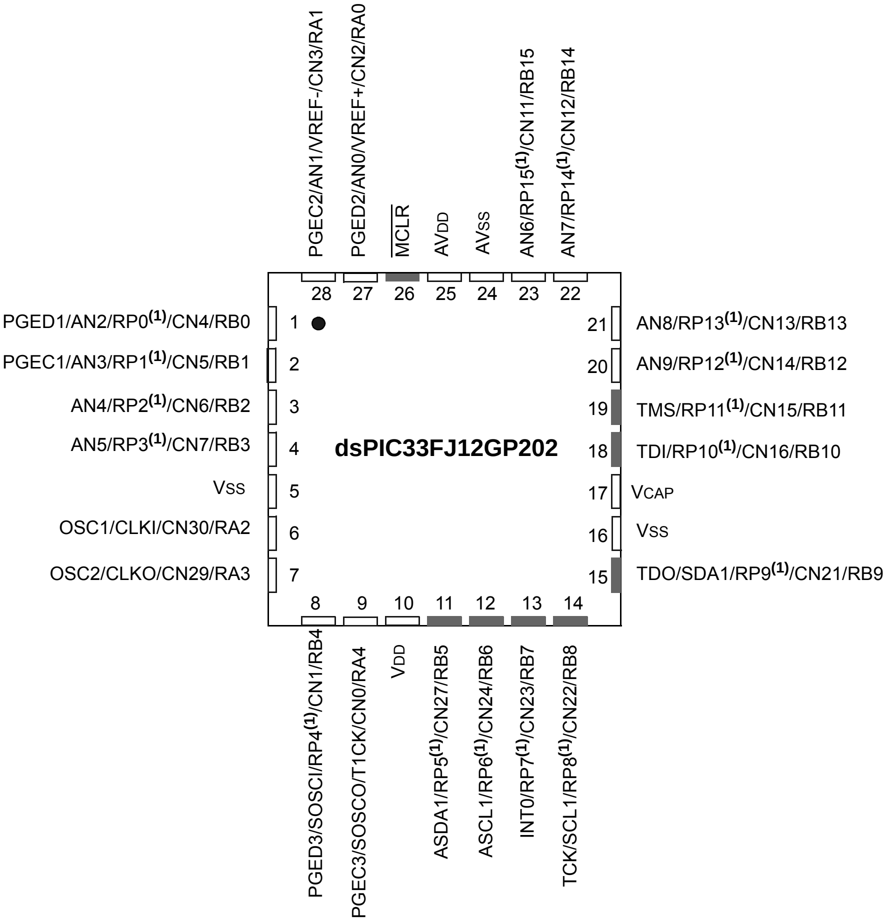
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj12gp202t-i-so

Pin Diagrams (Continued)

28-Pin QFN[2]

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

1.0 DEVICE OVERVIEW

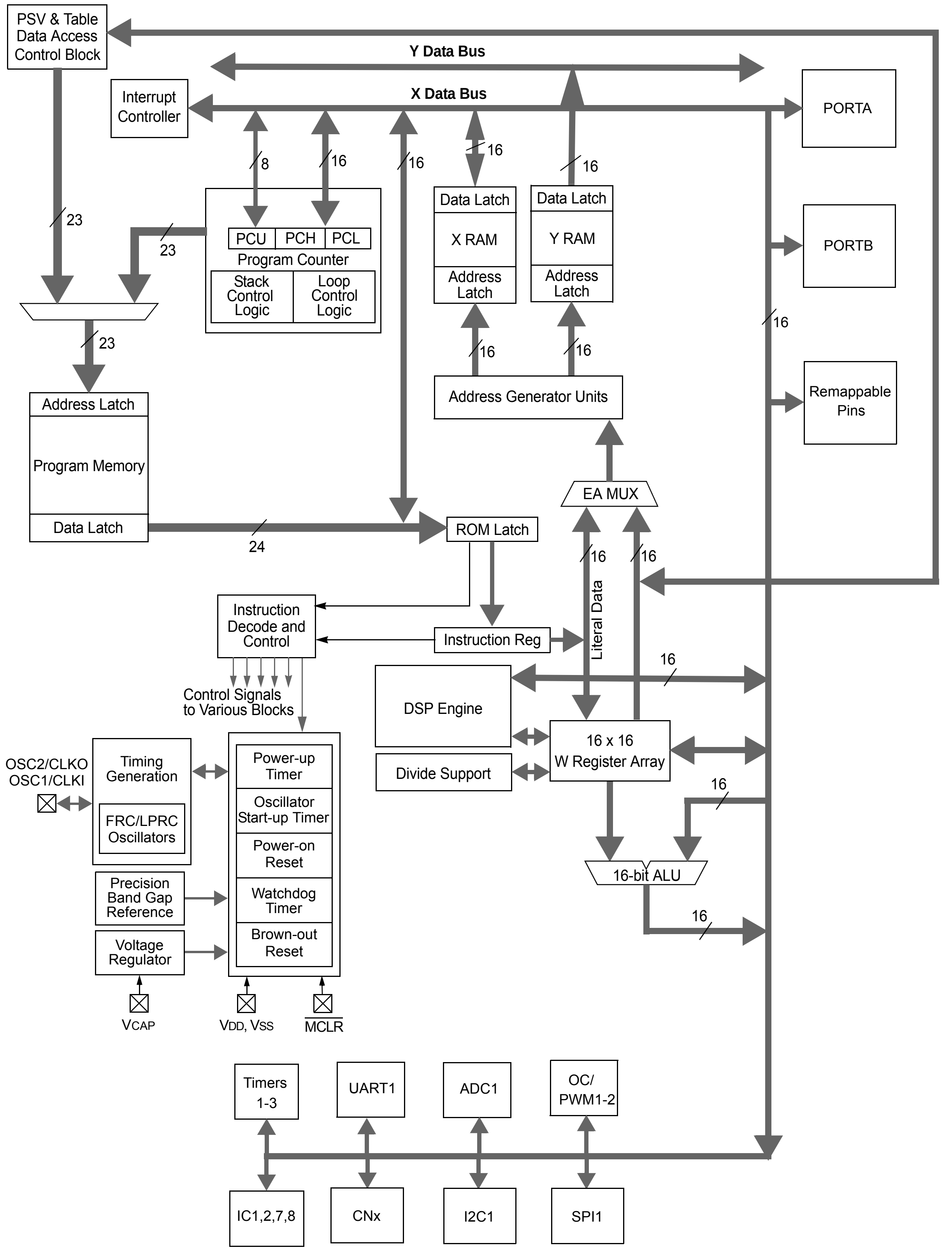
Note 1: This data sheet summarizes the features of the dsPIC33FJ12GP201/202 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device specific information for the dsPIC33FJ12GP201/202 Digital Signal Controller (DSC) devices. The dsPIC33F devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit microcontroller (MCU) architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules in the dsPIC33FJ12GP201/202 family of devices. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33FJ12GP201/202 BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See **"Pin Diagrams"** for the specific pins and features on each device.

TABLE 4-1: CPU CORE REGISTERS MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
WREG0	0000	Working Register 0																0000
WREG1	0002	Working Register 1																0000
WREG2	0004	Working Register 2																0000
WREG3	0006	Working Register 3																0000
WREG4	0008	Working Register 4																0000
WREG5	000A	Working Register 5																0000
WREG6	000C	Working Register 6																0000
WREG7	000E	Working Register 7																0000
WREG8	0010	Working Register 8																0000
WREG9	0012	Working Register 9																0000
WREG10	0014	Working Register 10																0000
WREG11	0016	Working Register 11																0000
WREG12	0018	Working Register 12																0000
WREG13	001A	Working Register 13																0000
WREG14	001C	Working Register 14																0000
WREG15	001E	Working Register 15																0800
SPLIM	0020	Stack Pointer Limit Register																xxxx
ACCAL	0022	Accumulator A Low Word Register																0000
ACCAH	0024	Accumulator A High Word Register																0000
ACCAU	0026	Accumulator A Upper Word Register																0000
ACCBL	0028	Accumulator B Low Word Register																0000
ACCBH	002A	Accumulator B High Word Register																0000
ACCBU	002C	Accumulator B Upper Word Register																0000
PCL	002E	Program Counter Low Word Register																0000
PCH	0030	—	—	—	—	—	—	—	—	Program Counter High Byte Register								0000
TBLPAG	0032	—	—	—	—	—	—	—	—	Table Page Address Pointer Register								0000
PSVPAG	0034	—	—	—	—	—	—	—	—	Program Memory Visibility Page Address Pointer Register								0000
RCOUNT	0036	Repeat Loop Counter Register																xxxx
DCOUNT	0038	DCOUNT<15:0>																xxxx
DOSTARTL	003A	DOSTARTL<15:1>															0	xxxx
DOSTARTH	003C	—	—	—	—	—	—	—	—	—	—	DOSTARTH<5:0>						00xx
DOENDL	003E	DOENDL<15:1>															0	xxxx
DOENDH	0040	—	—	—	—	—	—	—	—	—	—	DOENDH						00xx
SR	0042	OA	OB	SA	SB	OAB	SAB	DA	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000
CORCON	0044	—	—	—	US	EDT	DL<2:0>			SATA	SATB	SATDW	ACCSAT	IPL3	PSV	RND	IF	0020
MODCON	0046	XMODEN	YMODEN	—	—	BWM<3:0>				YWM<3:0>				XWM<3:0>				0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.6.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The `TBLRDL` and `TBLWTL` instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The `TBLRDH` and `TBLWTH` instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit-wide word address spaces, residing side by side, each with the same address range. `TBLRDL` and `TBLWTL` access the space that contains the least significant data word. `TBLRDH` and `TBLWTH` access the space that contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

- `TBLRDL` (Table Read Low): In Word mode, this instruction maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

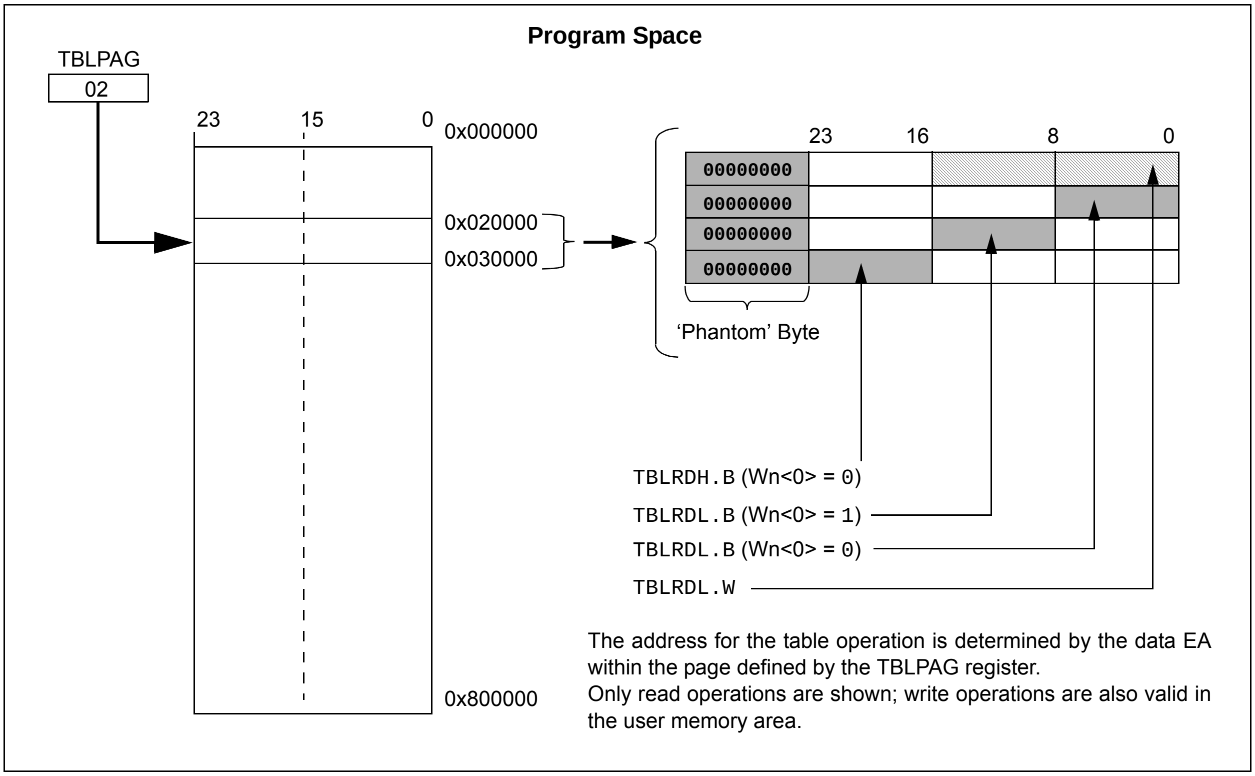
  In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is ‘`1`’; the lower byte is selected when it is ‘`0`’.
- `TBLRDH` (Table Read High): In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the ‘phantom byte’, will always be ‘`0`’.

  In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, as in the `TBLRDL` instruction. Note that the data will always be ‘`0`’ when the upper ‘phantom’ byte is selected (Byte Select = `1`).

In a similar fashion, two table instructions, `TBLWTH` and `TBLWTL`, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 “Flash Program Memory”**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = `0`, the table page is located in the user memory space. When TBLPAG<7> = `1`, the page is located in configuration space.

FIGURE 4-8: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register.
Only read operations are shown; write operations are also valid in the user memory area.

4.6.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of data space may optionally be mapped into any 16K word page of the program space. This option provides transparent access to stored constant data from the data space without the need to use special instructions (such as `TBLRDL` or `TBLRDH`).

Program space access through the data space occurs if the MSb of the data space EA is '`1`' and program space visibility is enabled by setting the PSV bit in the Core Control register (CORCON<2>). The location of the program memory space to be mapped into the data space is determined by the Program Space Visibility Page register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits. By incrementing the PC by 2 for each program memory word, the lower 15 bits of data space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads to this area add a cycle to the instruction being executed, since two program memory fetches are required.

Although each data space address 0x8000 and higher maps directly into a corresponding program memory address (see Figure 4-9), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space location used as data should be programmed with '`1111 1111`' or '`0000 0000`' to force a `NOP`. This prevents possible issues should the area of code ever be accidentally executed.

Note:	PSV access is temporarily disabled during table reads/writes.

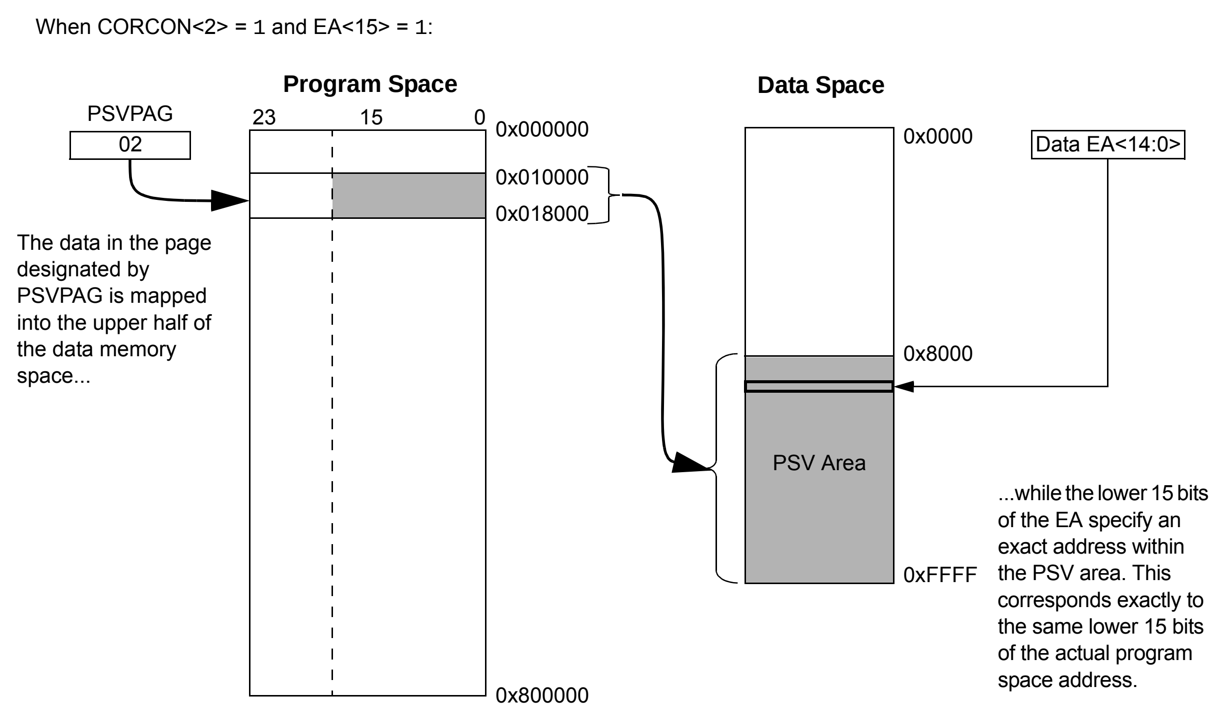
For operations that use PSV and are executed outside a `REPEAT` loop, the `MOV` and `MOV.D` instructions require one instruction cycle in addition to the specified execution time. All other instructions require two instruction cycles in addition to the specified execution time.

For operations that use PSV, and are executed inside a `REPEAT` loop, these instances require two instruction cycles in addition to the specified execution time of the instruction:

- Execution in the first iteration
- Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the `REPEAT` loop will allow the instruction using PSV to access data to execute in a single cycle.

FIGURE 4-9: PROGRAM SPACE VISIBILITY OPERATION



REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC<2:0>			—	NOSC<2:0>(2)		
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘`0`’

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
`111` = Fast RC oscillator (FRC) with Divide-by-n
`110` = Fast RC oscillator (FRC) with Divide-by-16
`101` = Low-Power RC oscillator (LPRC)
`100` = Secondary oscillator (SOSC)
`011` = Primary oscillator (XT, HS, EC) with PLL
`010` = Primary oscillator (XT, HS, EC)
`001` = Fast RC oscillator (FRC) with Divide-by-n plus PLL
`000` = Fast RC oscillator (FRC)

bit 11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
`111` = Fast RC oscillator (FRC) with Divide-by-n
`110` = Fast RC oscillator (FRC) with Divide-by-16
`101` = Low-Power RC oscillator (LPRC)
`100` = Secondary oscillator (SOSC)
`011` = Primary oscillator (XT, HS, EC) with PLL
`010` = Primary oscillator (XT, HS, EC)
`001` = Fast RC oscillator (FRC) with Divide-by-n plus PLL
`000` = Fast RC oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
If clock switching is enabled and FSCM is disabled (FOSC<FCKSM> = `0b01`)
`1` = Clock switching is disabled, system clock source is locked
`0` = Clock switching is enabled, system clock source can be modified by clock switching

bit 6 **IOLOCK:** Peripheral Pin Select Lock bit
`1` = Peripherial Pin Select is locked, write to peripheral pin select register is not allowed
`0` = Peripherial Pin Select is unlocked, write to peripheral pin select register is allowed

bit 5 **LOCK:** PLL Lock Status bit (read-only)
`1` = Indicates that PLL is in lock, or PLL start-up timer is satisfied
`0` = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

bit 4 **Unimplemented:** Read as ‘`0`’

Note 1: Writes to this register require an unlock sequence. Refer to **Section 7. “Oscillator”** (DS70186) in the *“dsPIC33F/PIC24H Family Reference Manual”* (available from the Microchip website) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

11.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33FJ12GP201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 11. “Timers”** (DS70205) of the *“dsPIC33F/PIC24H Family Reference Manual”*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer, which can serve as the time counter for the real-time clock, or operate as a free-running interval timer/counter. Timer1 can operate in three modes:

- 16-bit Timer
- 16-bit Synchronous Counter
- 16-bit Asynchronous Counter

Timer1 also supports these features:

- Timer gate operation
- Selectable prescaler settings
- Timer operation during CPU Idle and Sleep modes
- Interrupt on 16-bit Period register match or falling edge of external gate signal

Figure 11-1 presents a block diagram of the 16-bit timer module.

To configure Timer1 for operation:

1. Set the TON bit (= `1`) in the T1CON register.
2. Select the timer prescaler ratio using the TCKPS<1:0> bits in the T1CON register.
3. Set the Clock and Gating modes using the TCS and TGATE bits in the T1CON register.
4. Set or clear the TSYNC bit in T1CON to select synchronous or asynchronous operation.
5. Load the timer period value into the PR1 register.
6. If interrupts are required, set the interrupt enable bit, T1IE. Use the priority bits, T1IP<2:0>, to set the interrupt priority.

FIGURE 11-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM

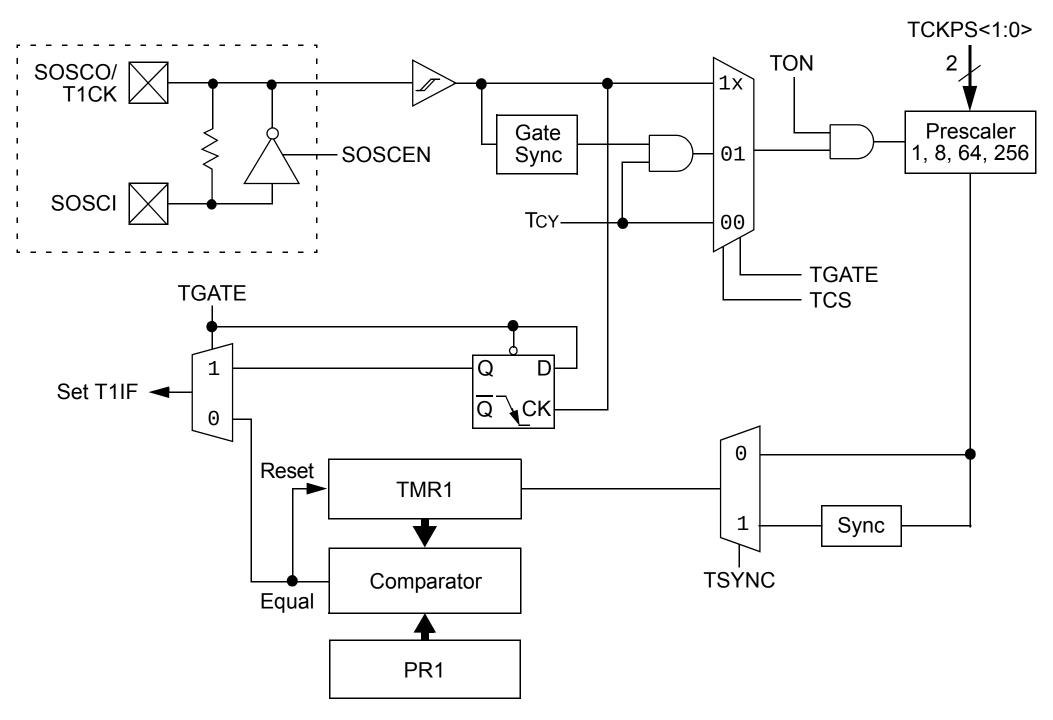
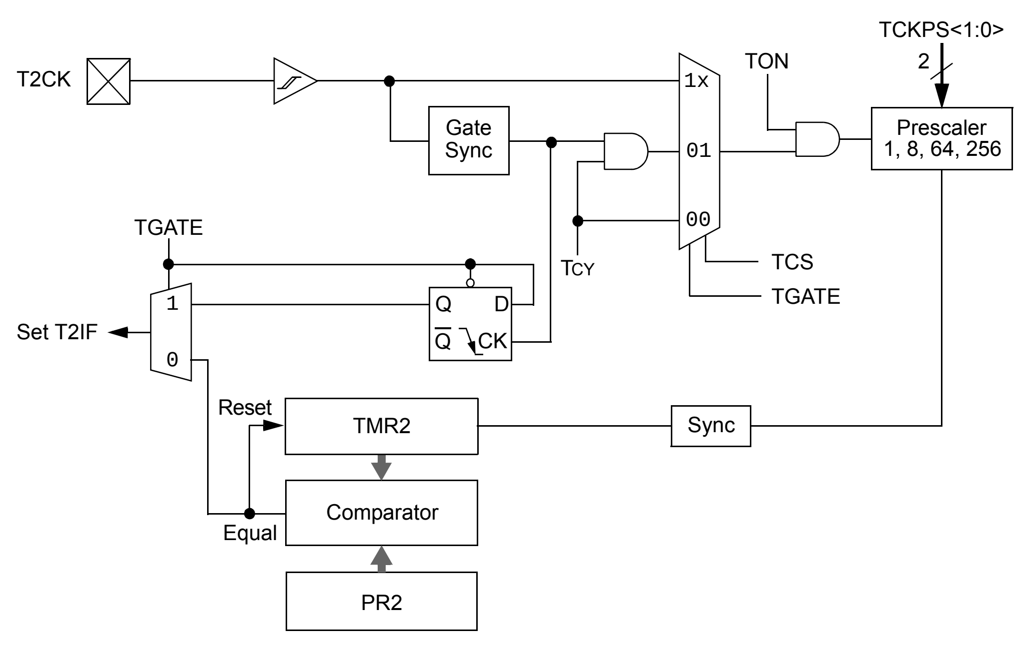


FIGURE 12-2: TIMER2 (16-BIT) BLOCK DIAGRAM



REGISTER 16-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10	**Unimplemented:** Read as ‘`0`’
bit 9-0	**AMSKx:** Mask for Address bit x Select bit `1` = Enable masking for bit x of incoming message address; bit match not required in this position `0` = Disable masking for bit x; bit match required in this position

TABLE 19-2: dsPIC33FJ12GP201/202 CONFIGURATION BITS DESCRIPTION

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection `1` = Boot segment may be written `0` = Boot segment is write-protected
BSS<2:0>	FBS	Immediate	Boot Segment Program Flash Code Protection Size `X11` = No Boot program Flash segment Boot space is 256 Instruction Words (except interrupt vectors) `110` = Standard security; boot program Flash segment ends at 0x0003FE `010` = High security; boot program Flash segment ends at 0x0003FE Boot space is 768 Instruction Words (except interrupt vectors) `101` = Standard security; boot program Flash segment, ends at 0x0007FE `001` = High security; boot program Flash segment ends at 0x0007FE Boot space is 1792 Instruction Words (except interrupt vectors) `100` = Standard security; boot program Flash segment ends at 0x000FFE `000` = High security; boot program Flash segment ends at 0x000FFE
GSS<1:0>	FGS	Immediate	General Segment Code-Protect bit `11` = User program memory is not code-protected `10` = Standard security `0x` = High security
GWRP	FGS	Immediate	General Segment Write-Protect bit `1` = User program memory is not write-protected `0` = User program memory is write-protected
IESO	FOSCSEL	Immediate	Two-speed Oscillator Start-up Enable bit `1` = Start-up device with FRC, then automatically switch to the user-selected oscillator source when ready `0` = Start-up device with user-selected oscillator source
FNOSC<2:0>	FOSCSEL	If clock switch is enabled, RTSP effect is on any device Reset; otherwise, Immediate	Initial Oscillator Source Selection bits `111` = Internal Fast RC (FRC) oscillator with postscaler `110` = Internal Fast RC (FRC) oscillator with divide-by-16 `101` = LPRC oscillator `100` = Secondary (LP) oscillator `011` = Primary (XT, HS, EC) oscillator with PLL `010` = Primary (XT, HS, EC) oscillator `001` = Internal Fast RC (FRC) oscillator with PLL `000` = FRC oscillator
FCKSM<1:0>	FOSC	Immediate	Clock Switching Mode bits `1x` = Clock switching is disabled, fail-safe clock monitor is disabled `01` = Clock switching is enabled, fail-safe clock monitor is disabled `00` = Clock switching is enabled, fail-safe clock monitor is enabled
IOL1WAY	FOSC	Immediate	Peripheral Pin Select Configuration `1` = Allow only one reconfiguration `0` = Allow multiple reconfigurations
OSCIOFNC	FOSC	Immediate	OSC2 Pin Function bit (except in XT and HS modes) `1` = OSC2 is clock output `0` = OSC2 is general purpose digital I/O pin
POSCMD<1:0>	FOSC	Immediate	Primary Oscillator Mode Select bits `11` = Primary oscillator disabled `10` = HS Crystal Oscillator mode `01` = XT Crystal Oscillator mode `00` = EC (External Clock) mode

20.0 INSTRUCTION SET SUMMARY

> **Note:** This data sheet summarizes the features of the dsPIC33FJ12GP201/202 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

The dsPIC33F instruction set is identical to that of the dsPIC30F.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 20-1 shows the general symbols used in describing the instructions.

The dsPIC33F instruction set summary in Table 20-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The `MAC` class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write back destination

The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the table read and table write instructions

21.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

21.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

21.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

21.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

21.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

21.10 PICkit 3 In-Circuit Debugger/Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

TABLE 22-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ[1]**	**Max**	**Units**	**Conditions**
	I_{IL}	**Input Leakage Current[2,3]**					
DI50		I/O Pins 5V Tolerant[4]	—	—	±2	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant[4]	—	—	±1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant[4]	—	—	±2	μA	Shared with external reference pins, -40°C ≤ T_A ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant[4]	—	—	±3.5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant[4]	—	—	±8	μA	Analog pins shared with external reference pins, -40°C ≤ T_A ≤ +125°C
DI55		$\overline{\text{MCLR}}$	—	—	±2	μA	$V_{SS} \le V_{PIN} \le V_{DD}$
DI56		OSC1	—	—	±2	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT and HS modes

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **“Pin Diagrams”** for a list of 5V tolerant pins.

5: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

6: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

10: These parameters are characterized, but not tested.

FIGURE 22-2: EXTERNAL CLOCK TIMING

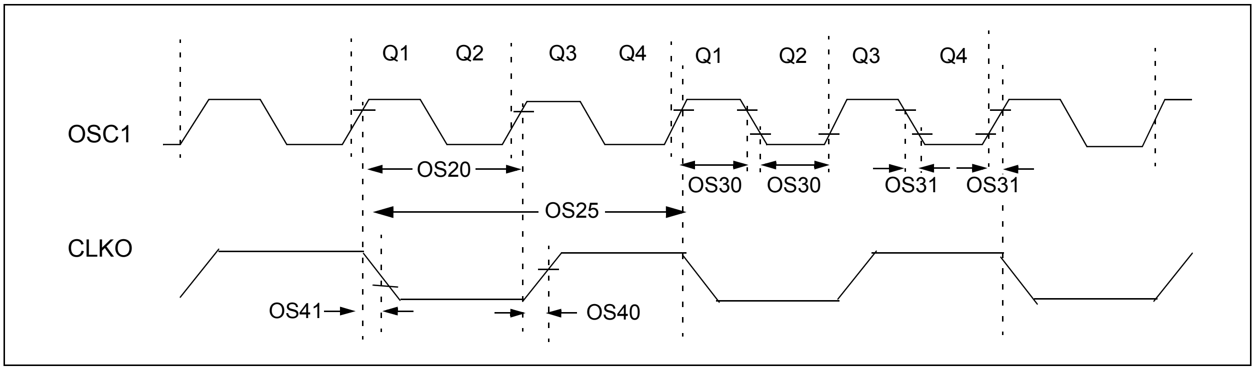


TABLE 22-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symb**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	40	MHz	EC
		Oscillator Crystal Frequency	3.5 10 —	— — —	10 40 33	MHz MHz kHz	XT HS SOSC
OS20	TOSC	TOSC = 1/FOSC(4)	12.5	—	DC	ns	
OS25	TCY	Instruction Cycle Time(2,4)	25	—	DC	ns	
OS30	TosL, TosH	External Clock in (OSC1)(5) High or Low Time	0.375 x TOSC	—	0.625 x TOSC	ns	EC
OS31	TosR, TosF	External Clock in (OSC1)(5) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3,5)	—	5.2	—	ns	
OS41	TckF	CLKO Fall Time(3,5)	—	5.2	—	ns	
OS42	GM	External Oscillator Transconductance(6)	14	16	18	mA/V	VDD = 3.3V TA = +25ºC

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: Instruction cycle period (TCY) equals two times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits can result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

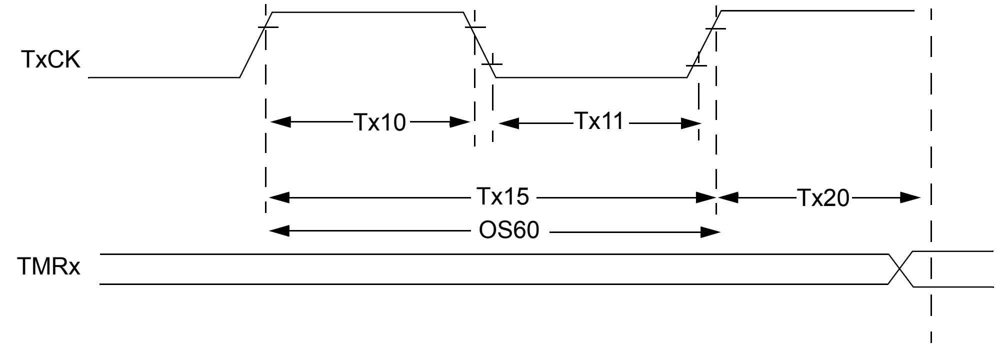
3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: These parameters are characterized by similarity, but are tested in manufacturing at FIN = 40 MHz only.

5: These parameters are characterized by similarity, but are not tested in manufacturing.

6: Data for this parameter is preliminary. This parameter is characterized, but is not tested in manufacturing.

FIGURE 22-5: TIMER1, 2, 3 AND 4 EXTERNAL CLOCK TIMING CHARACTERISTICS



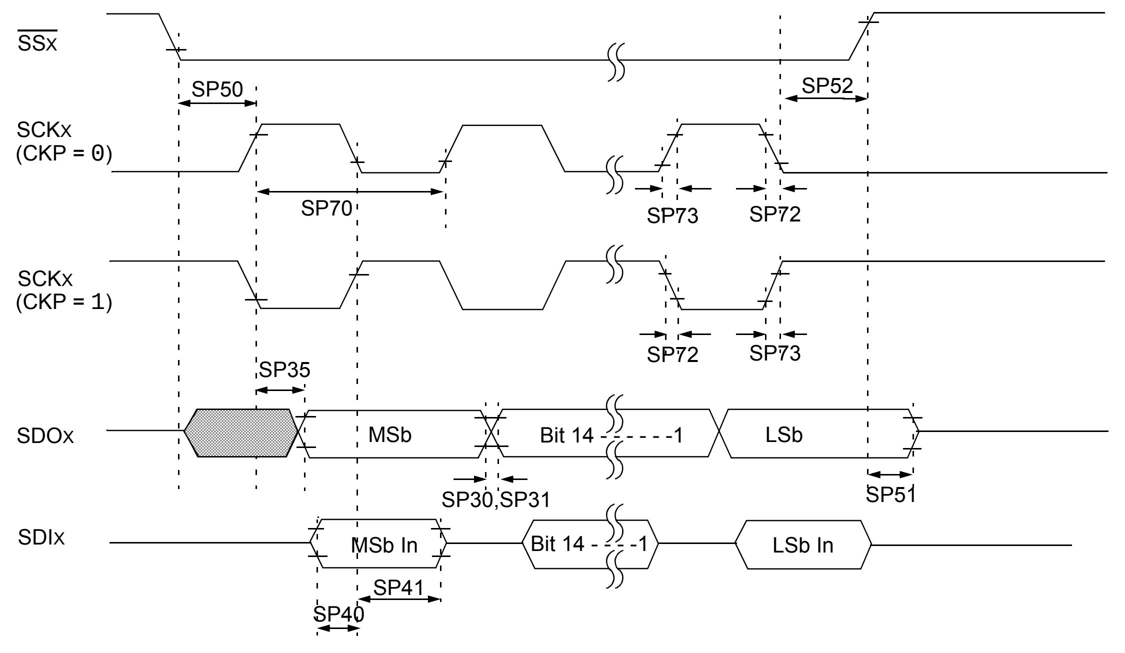
Note: Refer to Figure 22-1 for load conditions.

TABLE 22-22: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS[1]

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TA10	TTXH	TxCK High Time	Synchronous, no prescaler	TCY + 20	—	—	ns	Must also meet parameter TA15. N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	(TCY + 20)/N	—	—	ns	
			Asynchronous	20	—	—	ns	
TA11	TTXL	TxCK Low Time	Synchronous, no prescaler	(TCY + 20)	—	—	ns	Must also meet parameter TA15. N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	(TCY + 20)/N	—	—	ns	
			Asynchronous	20	—	—	ns	
TA15	TTXP	TxCK Input Period	Synchronous, no prescaler	2 TCY + 40	—	—	ns	—
			Synchronous, with prescaler	Greater of: 40 ns or (2 TCY + 40)/N	—	—	—	N = prescale value (1, 8, 64, 256)
			Asynchronous	40	—	—	ns	—
OS60	Ft1	SOSCI/T1CK Oscillator Input frequency Range (oscillator enabled by setting bit TCS (T1CON<1>))		DC	—	50	kHz	—
TA20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40		1.75 TCY + 40	—	—

Note 1: Timer1 is a Type A.

FIGURE 22-15: SPIx SLAVE MODE (FULL-DUPLEX CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 22-1 for load conditions.

TABLE 22-35: SPIx SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance[4]	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

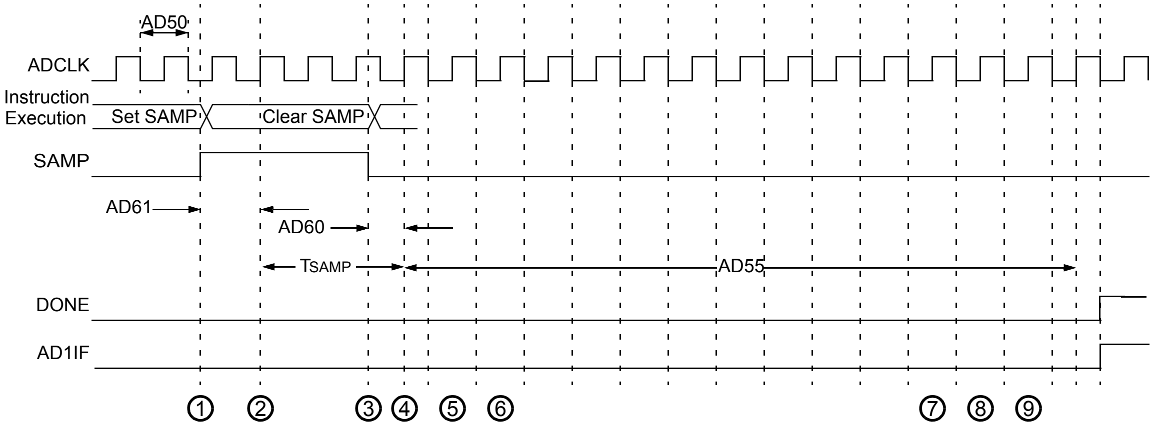
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 22-21: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS (ASAM = `0`, SSRC<2:0> = `000`)



① – Software sets AD1CON. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **Section 16. “Analog-to-Digital Converter (ADC)”** (DS70183) in the *“dsPIC33F/PIC24H Family Reference Manual*.

③ – Software clears AD1CON. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

⑤ – Convert bit 11.

⑥ – Convert bit 10.

⑦ – Convert bit 1.

⑧ – Convert bit 0.

⑨ – One TAD for end of conversion.

TABLE 22-41: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Clock Parameters(1)							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14 TAD		ns	
AD56	FCNV	Throughput Rate	—	—	500	Ksps	
AD57	TSAMP	Sample Time	3.0 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2.0 TAD	—	3.0 TAD	—	Auto Convert Trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2.0 TAD	—	3.0 TAD	—	—
AD62	tCSS	Conversion Completion to Sample Start (ASAM = `1`)(2)	—	0.5 TAD	—	—	—
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2)	—	—	20	µs	—

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: These parameters are characterized but not tested in manufacturing.